



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  *: Required Field

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-07-14
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	IPD MD Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	A59U*UR36AD6	A	MU1A	2015-07-14
Amount	UoM	Unit type	ST ECOPACK Grade	
653.38	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	250	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	15.46X7.55x2.28	30	gull wing	
Comment	Package: SO 24 .30 TO JEDEC MS-013AD, MD valid for CP:L6226D,L6226DTR.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	A59U*UR36AD6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	9.476	mg	supplier	die	Silicon (Si)	7440-21-3		9.193	mg	970132	14068
				supplier	metallization	Aluminium (Al)	7429-90-5		0.069	mg	7282	106
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	844	12
				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.02	mg	2111	31
				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.119	mg	12559	182
				supplier	passivation	Gamma-butyrolactone	96-48-0		0.04	mg	4222	61
				supplier	passivation	Polyhydroxyamide	55295-98-2		0.018	mg	1900	28
				supplier	passivation	Alcoxysilane	proprietary		0.001	mg	106	2
				supplier	passivation	Aryl Siliclic Acid	proprietary		0.001	mg	106	2
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.001	mg	106	2
				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	106	2
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.005	mg	528	8
Leadframe	Copper & its alloys	199.876	mg	supplier	alloy	Copper (Cu)	7440-50-8		199.538	mg	998309	305393
				supplier	alloy	Iron (Fe)	7439-89-6		0.092	mg	460	141
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.168	mg	841	257
				supplier	metallization	Nickel (Ni)	7440-02-0		0.071	mg	355	109
				supplier	metallization	Palladium (Pd)	7440-05-3		0.005	mg	25	8
				supplier	metallization	Gold (Au)	7440-57-5		0.002	mg	10	3
Die attach	Other Organic Materials	1.732	mg	supplier	glue	Silver (Ag)	7440-22-4		1.299	mg	750000	1988
				supplier	glue	Epoxy Cresol Novolak	29690-82-2		0.428	mg	247113	655
				supplier	glue	tert-butanol	75-65-0		0.002	mg	1155	3
				supplier	glue	1-isopropyl-2,2-dimethyltrimethylene diisobu	6846-50-0		0.003	mg	1732	5
Bonding wire	Other inorganic materials	0.975		supplier	wire	Gold (Au)	7440-57-5		0.975	mg	1000000	1492
Encapsulation	Other Organic Materials	441.321	mg	supplier	mold compound	Silica, vitreous	60676-86-0		353.057	mg	800000	540355
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		30.893	mg	70001	47282
				supplier	mold compound	Phenol resin	9003-35-4		17.653	mg	40000	27018
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		26.479	mg	59999	40526
				supplier	mold compound	Antimony Trioxide	1309-64-4		5.296	mg	12000	8106
				JIG 1	mold compound	Brominated Epoxy Resin	40039-93-8		6.619	mg	14998	10130
				supplier	mold compound	Carbon black	1333-86-4		1.324	mg	3000	2026